

ABSTRACT

A method for solder bonding a photodiode or an array of photodiodes to a substrate, the photodiode(s) tilted at a predetermined angle, uses a pair solder bumps placed on a photodiode chip opposite a corresponding pair of solder pads placed on the substrate. When the photodiode chip is placed on the substrate, with the solder bumps therebetween, the solder is melted and undergoes a reflow over the surface of the pads. The shape of the pads and the location of the solder bumps on the pads causes the surface tension of the solder to tilt the chip by pulling it to one side.

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